



AI-Enabled Internet of Things for Engineering Applications

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Message from the Guest Editors

Dear Colleagues,

The synergetic relationship between Artificial Intelligence (AI) and Internet of Things (IoT) enables disruptive innovations in wearables and implantable devices for numerous engineering applications. The three key components of this emerging era of AI and IoT applications are (i) intelligent sensors, information and knowledge, (ii) intelligent systems-of-systems, and (iii) advanced end-to-end analytics. There are several research challenges in implementing AI-enabled IoT systems and applications. From a system and application front, there is a need to design intelligent and scalable data solutions and analytics facilitated by collaborative sensing and collaborative machine learning algorithms. For this reason, this Special Issue aims to solicit submissions of unpublished and original research articles that present in-depth fundamental research contributions from a methodological or theoretical application perspective containing novel algorithms, architectures, techniques, or systems that offer new insights and findings in the field of AI-empowered IoT.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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